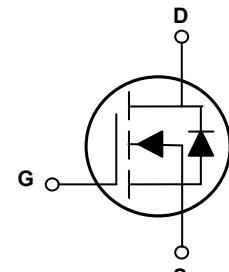


## Main Product Characteristics

$V_{(BR)DSS}$	40V
$R_{DS(ON)}$	20mΩ (max.)
$I_D$	30A



PPAK3x3



Schematic Diagram

## Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



## Description

The GSFN4020 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

## Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	$V_{DS}$	40	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous ( $T_A=25^\circ\text{C}$ )	$I_D$	30	A
Drain Current-Continuous ( $T_A=70^\circ\text{C}$ )		21	A
Drain Current-Pulsed <sup>1</sup>	$I_{DM}$	120	A
Single Pulse Avalanche Energy <sup>2</sup>	$E_{AS}$	4.9	mJ
Single Pulse Avalanche Current <sup>2</sup>	$I_{AS}$	10	A
Power Dissipation ( $T_A=25^\circ\text{C}$ )	$P_D$	45	W
Power Dissipation-Derate Above 25°C		0.36	W/°C
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	2.77	°C/W
Storage Temperature Range	$T_{STG}$	-50 To +150	°C
Operating Junction Temperature Range	$T_J$	-50 To +150	°C

**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>On / Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	40	-	-	V
Drain-Source Leakage Current	$I_{\text{DSS}}$	$V_{\text{DS}}=40\text{V}, V_{\text{GS}}=0\text{V}, T_J=25^\circ\text{C}$	-	-	1	$\mu\text{A}$
		$V_{\text{DS}}=32\text{V}, V_{\text{GS}}=0\text{V}, T_J=125^\circ\text{C}$	-	-	10	$\mu\text{A}$
Gate-Source Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm 100$	nA
Static Drain-Source On-Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=8\text{A}$	-	16	20	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=4\text{A}$	-	20	26	
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1.1	1.6	2.8	V
Forward Transconductance	$g_{\text{fs}}$	$V_{\text{DS}}=10\text{V}, I_{\text{D}}=1\text{A}$	-	4.5	-	S
<b>Dynamic and Switching Characteristics</b>						
Total Gate Charge <sup>2,3</sup>	$Q_g$	$V_{\text{DS}}=32\text{V}, I_{\text{D}}=3\text{A}, V_{\text{GS}}=10\text{V}$	-	10.8	-	nC
Gate-Source Charge <sup>2,3</sup>	$Q_{\text{gs}}$		-	1.6	-	
Gate-Drain Charge <sup>2,3</sup>	$Q_{\text{gd}}$		-	3.3	-	
Turn-On Delay Time <sup>2,3</sup>	$t_{\text{d(on)}}$	$V_{\text{DD}}=15\text{V}, R_{\text{G}}=3.3\Omega, V_{\text{GS}}=10\text{V}, I_{\text{D}}=1\text{A}$	-	3.8	-	nS
Rise Time <sup>2,3</sup>	$t_r$		-	10.5	-	
Turn-Off Delay Time <sup>2,3</sup>	$t_{\text{d(off)}}$		-	22.2	-	
Fall Time <sup>2,3</sup>	$t_f$		-	6.6	-	
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=25\text{V}, V_{\text{GS}}=0\text{V}, F=1\text{MHz}$	-	800	-	pF
Output Capacitance	$C_{\text{oss}}$		-	71	-	
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	110	-	
Gate Resistance	$R_g$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=0\text{V}, F=1\text{MHz}$	-	2.6	-	$\Omega$
<b>Source-Drain Ratings and Characteristics</b>						
Continuous Source Current	$I_s$	Force Current	-	-	30	A
Pulsed Source Current	$I_{\text{SM}}$		-	-	120	A
Diode Forward Voltage	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=1\text{A}, T_J=25^\circ\text{C}$	-	-	1	V
Reverse Recovery Time	$T_{\text{rr}}$	$V_R=30\text{V}, I_S=8\text{A}, \frac{di}{dt}=100\text{A}/\mu\text{s}, T_J=25^\circ\text{C}$	-	33	-	nS
Reverse Recovery Charge	$Q_{\text{rr}}$		-	12	-	nC

Notes:

- Repetitive rating: Pulsed width limited by maximum junction temperature.
- $V_{\text{DD}}=25\text{V}, V_{\text{GS}}=10\text{V}, L=0.1\text{mH}, I_{\text{AS}}=9.9\text{A}, R_{\text{G}}=25\Omega$ , Starting  $T_J=25^\circ\text{C}$ .
- The data tested by pulsed, pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .
- Essentially independent of operating temperature.

## Typical Electrical and Thermal Characteristic Curves

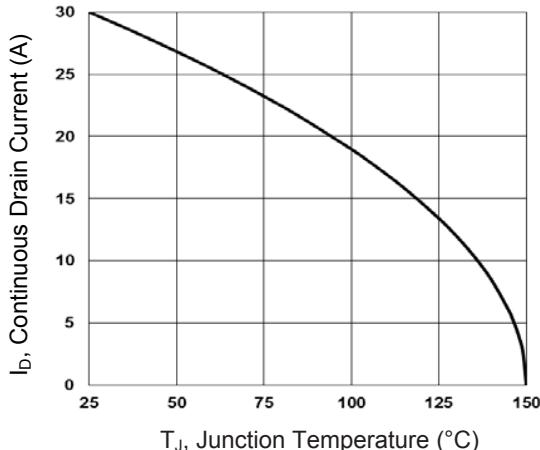


Figure 1. Continuous Drain Current vs. T<sub>J</sub>

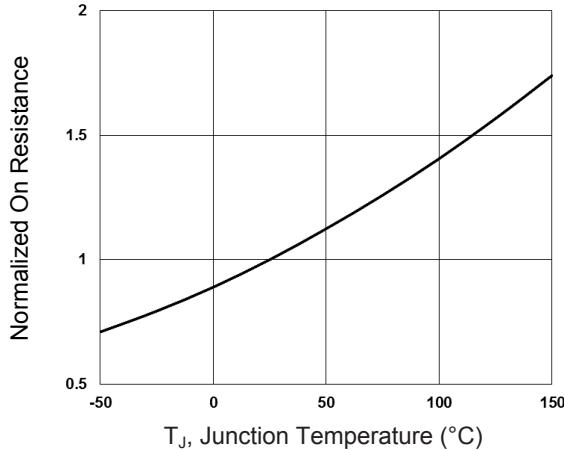


Figure 2. Normalized R<sub>DS(ON)</sub> vs. T<sub>J</sub>

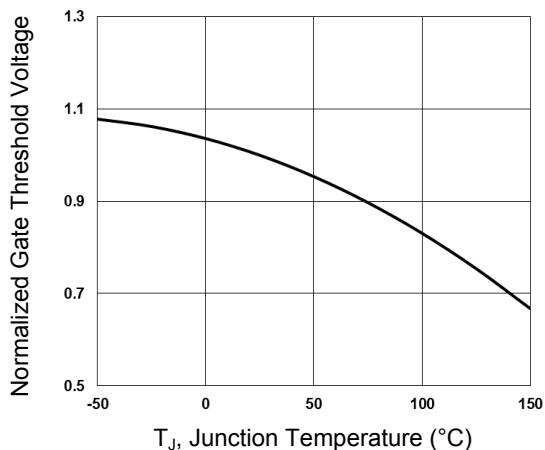


Figure 3. Normalized V<sub>th</sub> vs. T<sub>J</sub>

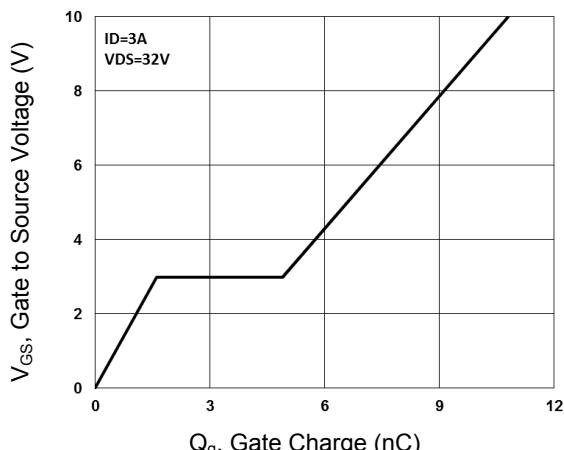


Figure 4. Gate Charge Waveform

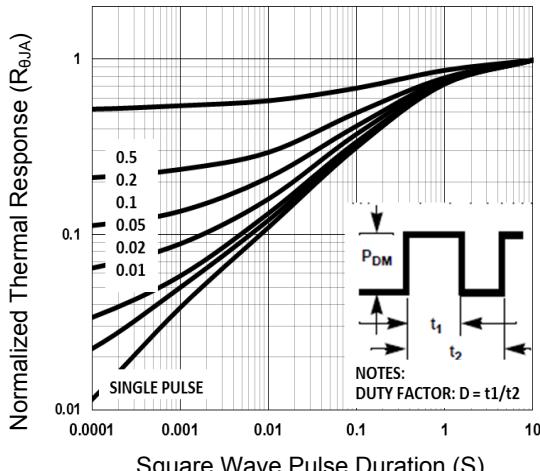


Figure 5. Normalized Transient Impedance

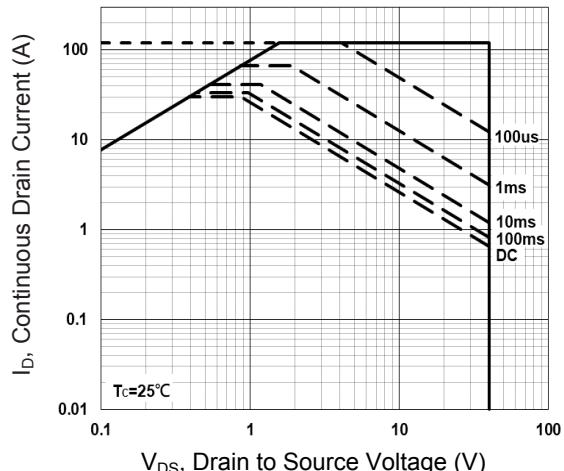
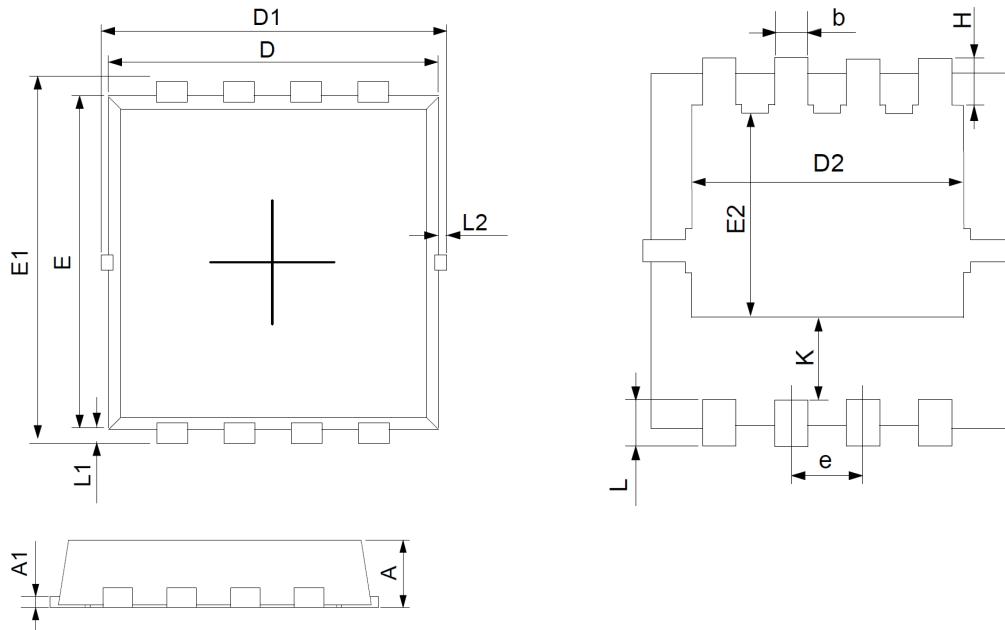


Figure 6. Maximum Safe Operation Area

### Package Outline Dimensions (PPAK3x3)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.70	0.90	0.028	0.035
A1	0.14	0.20	0.006	0.008
D	3.05	3.25	0.120	0.128
E	2.90	3.10	0.114	0.122
D1	3.10	3.50	0.122	0.138
D2	2.35	2.50	0.093	0.098
E1	3.10	3.50	0.122	0.138
E2	1.64	1.84	0.065	0.072
b	0.25	0.35	0.010	0.014
k	0.59	0.79	0.023	0.031
e	0.55	0.75	0.022	0.030
E4	3.34	3.92	0.131	0.154
L	0.25	0.55	0.010	0.022
L1	0.10	0.20	0.004	0.008
H	0.32	0.52	0.013	0.020

### Order Information

Device	Package	Marking	Carrier	Quantity
GSFN4020	PPAK3x3	N4020	Tape & Reel	5,000 pcs / Reel

For more information, please contact us at: [inquiry@goodarksemi.com](mailto:inquiry@goodarksemi.com)